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(54) Title: SEMICONDUCTOR CHAMBER COMPONENTS WITH MULTI-LAYER COATING

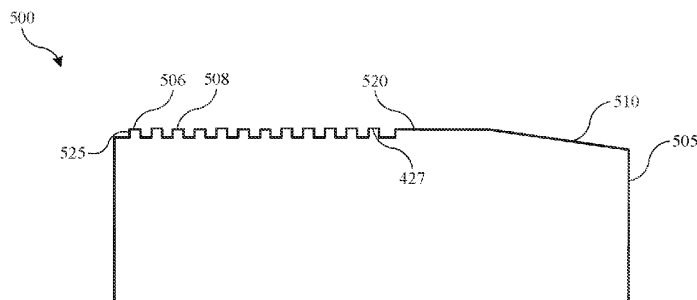


FIG. 5

(57) Abstract: Exemplary semiconductor processing chambers may include a chamber body. The chambers may include a showerhead. The chambers may include a substrate support. The substrate support may include a platen characterized by a first surface facing the showerhead. The substrate support may include a shaft coupled with the platen along a second surface of the platen opposite the first surface of the platen. The shaft may extend at least partially through the chamber body. A coating may extend conformally about the first surface of the platen. The coating may include a first layer of silicon proximate the first surface of the platen, and may include a second layer of material overlying the first layer of silicon.



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